

Two-Step LED Current Controller with Line Regulation Compensation

Description

The **XR46203** is a two-step LED current controller with line regulation compensation for operating over a wide alternative current (AC) voltage source range. It can drive an external N-channel power MOSFET to regulate the current flowing through a high voltage (HV) LED string.

The XR46203 works as a constant current sink with linear type over voltage protection (OVP), linear type over temperature protection (OTP), and line regulation compensation. It is suitable for applications with a rectified AC voltage source.

The PCB design can be very compact to meet various shape requirements. It is especially suitable for replacing incandescent light bulb and linear type fluorescent lamps.

Typical Application

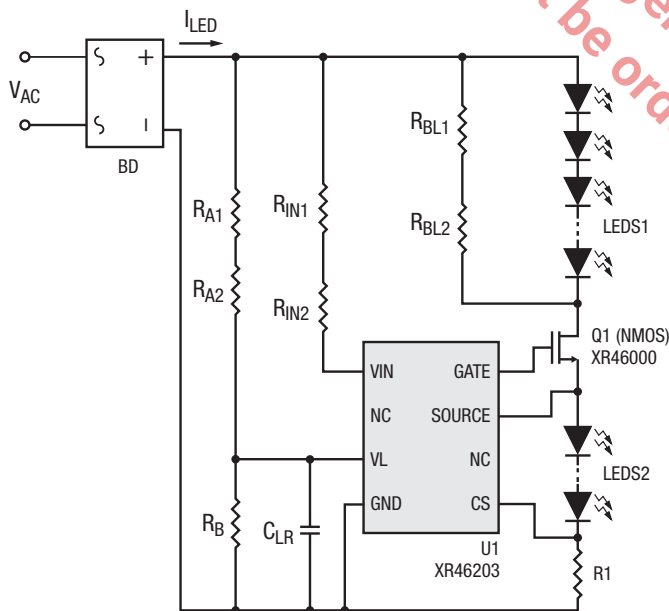


Figure 1. Typical 2-Step Application

FEATURES

- Device
 - Two current step control from single device
 - Excellent system power regulation over AC line variation range
 - 6V to 78V chip supply voltage range
 - Over temperature protection
 - Over voltage protection
 - 3mm x 3mm TDFN-8 package
- System
 - Single board LED lighting solution available
 - All solid state components
 - No electrolytic capacitor or MOV required
 - Scalable architecture allows optimization of performance vs. cost
 - Driver-on-board and chip-on-board design solution available which minimize process flow and assembly cost
 - High PF and low THD performance
 - Flexible PCB layout options
 - TRIAC dimmable

APPLICATIONS

- LED Lighting Applications
 - Downlight
 - High bay
 - Specialty
 - Architectural

Absolute Maximum Ratings

Stresses beyond the limits listed below may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

Sustaining Voltage

VIN, GATE, Source to GND	-0.3V to 85V
GATE to Source	-0.3V to 7V
Source to CS	-0.3V to 70V
VL to GND	-0.3V to 7V
CS to GND	-0.3V to 1V
VIN Input Current	3mA
Source to CS Current	180mA
Maximum Operating Junction Temperature, T_J	150°C
Operating Temperature, T_{opr}	-40°C to 85°C
Storage Temperature Range	-55°C to 150°C
Lead Temperature (Soldering, 10 seconds)	260°C

NOTE:

1. All voltages are with respect to Ground. Currents are positive into, negative out of the specified terminal.
2. All parameters having Min/Max specifications are guaranteed. Typical values are for reference purpose only.
3. Unless otherwise noted, all tests are pulsed tests at the specified temperature, therefore: $T_J = T_C = T_A$.

Operating Conditions

Input Voltage, V_{IN}	6 to 78V
Peak Level Current, I_{PEAK}	20 to 180mA

Electrical Characteristics

Unless otherwise noted, typical values are at $T_A = 25^\circ\text{C}$.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
$V_{IN_{MIN}}$	Minimum VIN supply voltage		6			V
I_{IN}	VIN supply current	$V_{IN} = 6V \text{ to } 73V$		0.3		mA
$V_{IN_{Clamp}}$	VIN over voltage clamp	When $V_{IN} > V_{IN_{Clamp}}$, I_{IN} will increase to $> 1mA$ to clamp VIN at $V_{IN_{Clamp}}$	74	76	80	V
V_{CS}	CS voltage	$V_{VL} = 1.75V$	244	250	256	mV
ΔV_{LR1}	CS voltage line regulation vs. $V_{VL}^{(1)}$	$V_{VL} = 1.57V \text{ to } 1.75V$		-0.28		mV/mV
ΔV_{LR2}		$V_{VL} = 1.75V \text{ to } 2.10V$		-0.24		
ΔV_{LR3}		$V_{VL} = 2.10V \text{ to } 2.28V$		-0.3		
V_{REF1}/V_{REF0}	Reference voltage ratio		86	90	94	%
$V_{CS_{Clamp}}$	Maximum V_{CS} clamp	V_L under voltage protection, $V_{VL} < 1.45V$	310	323	336	mV
V_{Gate}	Gate voltage	Gate to Source		5.4		V
I_{SOURCE}	GATE source current ⁽²⁾	$V_{Gate} - V_{Source} = 3V$		30		μA
I_{SINK}	GATE sink current ⁽²⁾	$V_{Gate} - V_{Source} = 3V$		500		
T_{TP}	Thermal protection trip temperature ⁽²⁾	When T_J is higher than T_{TP} , V_{CS} decreases linearly	135	145		$^\circ\text{C}$
$\Delta V_{CS}/\Delta T_J$	Thermal protection mode V_{CS} decreasing slope ⁽²⁾	$T_J > T_{TP}$		-1.1		$\%/^\circ\text{C}$

NOTES:

1. The CS voltage line regulation is defined as:

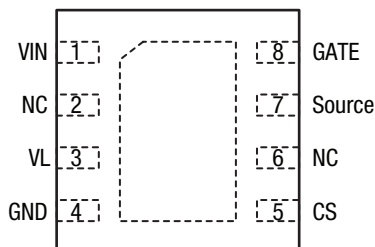
$$\Delta V_{LR1} = \frac{\Delta V_{CS}}{\Delta V_{VL}} = \frac{V_{CS}(V_{VL} = 1.75V) - V_{CS}(V_{VL} = 1.57V)}{1.75V - 1.57V}$$

$$\Delta V_{LR2} = \frac{\Delta V_{CS}}{\Delta V_{VL}} = \frac{V_{CS}(V_{VL} = 2.10V) - V_{CS}(V_{VL} = 1.75V)}{2.10V - 1.75V}$$

$$\Delta V_{LR3} = \frac{\Delta V_{CS}}{\Delta V_{VL}} = \frac{V_{CS}(V_{VL} = 2.28V) - V_{CS}(V_{VL} = 2.10V)}{2.28V - 2.10V}$$

2. Guarantee by design, not by production test.

Pin Configuration



3mm x 3mm TDFN-8, Top View

Pin Functions

Pin Number	Pin Name	Description
1	VIN	Power supply pin.
2	NC	No connection.
3	VL	Line regulation sense pin. The reference voltage is adjusted according to VL to provide the line regulation compensation and to provide over voltage protection.
4	GND	Ground pin.
5	CS	Current sense pin. Connect a sense resistor, R_{CS} , between this pin and the GND pin. The peak current is set by: $I_{OUT} = \frac{V_{CS}}{R_{CS}}$
6	NC	No connection.
7	Source	External HV NMOS source pin. The V_F of the LED segment connected between the source pin and the CS pin should not be higher than 70V.
8	GATE	External HV NMOS gate driving pin. Limited to 5.5V maximum.
Exposed Thermal Pad (EP)		Exposed thermal pad of the chip. Use this pad to enhance the power dissipation capability. The thermal conductivity will be improved if a copper foil on PCB is soldered with the thermal pad. It is recommended to connect the exposed thermal pad to the GND pin.

For a typical 2-step driving scheme using a single XR46203, the electrical performance is good enough to meet applications where the Power Factor (PF) is higher than 0.92 and the Total Harmonic Distortion (THD) is around 30%. If higher PF or lower THD is required, one more XR46083 or XR46084 can be added to the circuit to make a 3-step driving scheme, as shown in below. The 3-step system can provide better electrical performance with PF greater than 0.96 and THD approximately 20%. Line regulation, THD and PF performance are illustrated in Figures 5 and 6.

VAC (V)	THD (%)	PF
207	21	0.978
219	18	0.985
230	16.5	0.988
242	15.5	0.992
253	15.5	0.991
265	16.5	0.990

Line Regulation (%)

PIN Regulation

V_{AC} (V)

V_{AC} (V)	Line Regulation (%)
207	95
219	99
230	100
242	101
253	100
265	99



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Applications Information (Continued)

Linear Type Thermal Protection

When the junction temperature T_J rises to the Thermal Protection Trip Temperature T_{TP} (typically 145°C), the current sense voltage V_{CS} starts to decrease linearly at a slope of $-1.1\%/^{\circ}\text{C}$. The LED driving current decreases proportionally with the V_{CS} voltage. The system will function normally during the thermal protection mode with the lower driving current, but the power dissipation of the XR46203 chip will decrease until thermal equilibrium is reached.

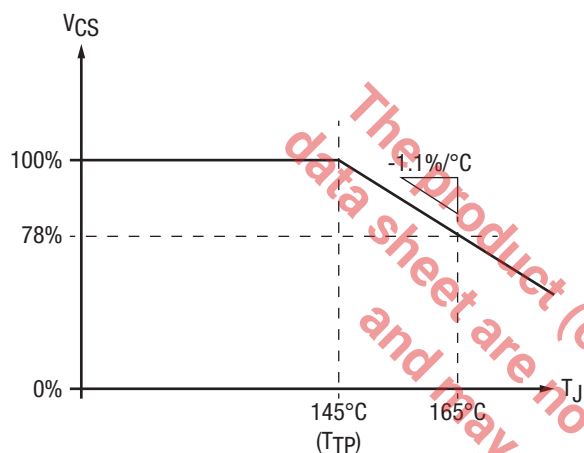


Figure 7. V_{CS} vs. T_J

Line Regulation Compensation

When there is variation in line voltage (V_{AC}), the power of the lamp will also change if the LED driving current is kept unchanged. In order to provide good line regulation when V_{AC} varies within a $\pm 20\%$ range, the average of the rectified V_{AC} is sensed by the V_L pin to provide compensation in order to attempt to keep the power of the lamp at the same level.

The LED driving current is adjusted as the voltage level V_{VL} at the V_L pin is changed. Based on the design, the LED driving current will be lower when V_{AC} is higher than the nominal value, and the LED driving current will be higher when V_{AC} is lower than the nominal value. The system power can then be maintained at approximately the same level. During power on, the driving current may be slightly higher for a few cycles until steady state is reached.

With the compensation function, the XR46203 provides excellent power line regulation over a $\pm 20\%$ V_{AC} variation range, as shown in Figures 8 and 9.

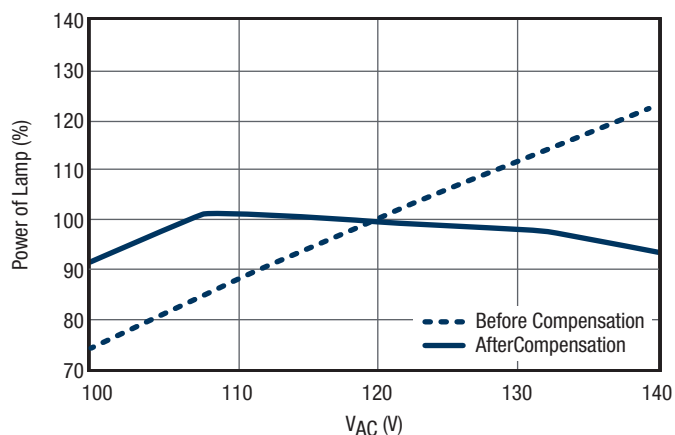


Figure 8. $120V_{AC}$ Power Line Regulation ($120V_{AC} \pm 15\%$)

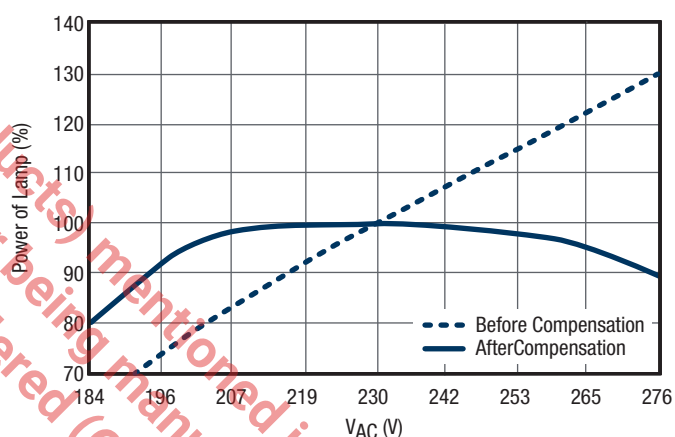


Figure 9. $230V_{AC}$ Power Line Regulation ($230V_{AC} \pm 20\%$)

Applications Information (Continued)

Layout Suggestion

The exposed thermal pad under the chip is used to enhance the power dissipation capability of the DFN package. The thermal conductivity will be improved if a copper foil on the PCB that is soldered to the thermal pad can be as large as possible. It is strongly recommended to connect the GND pin to the exposed thermal pad.

The external HV NMOS is also recommended to be placed close to the XR46203. In addition, the current sense resistor connected between the CS pin and GND pin should be placed as close as possible to the CS pin and GND pin, as the example in below.

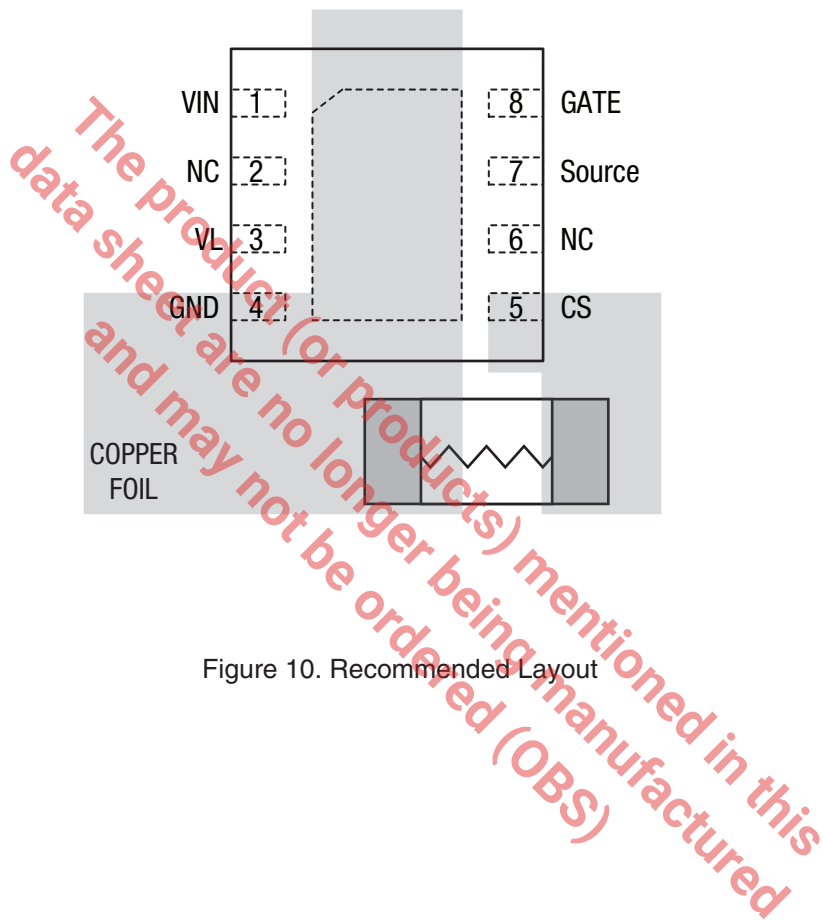
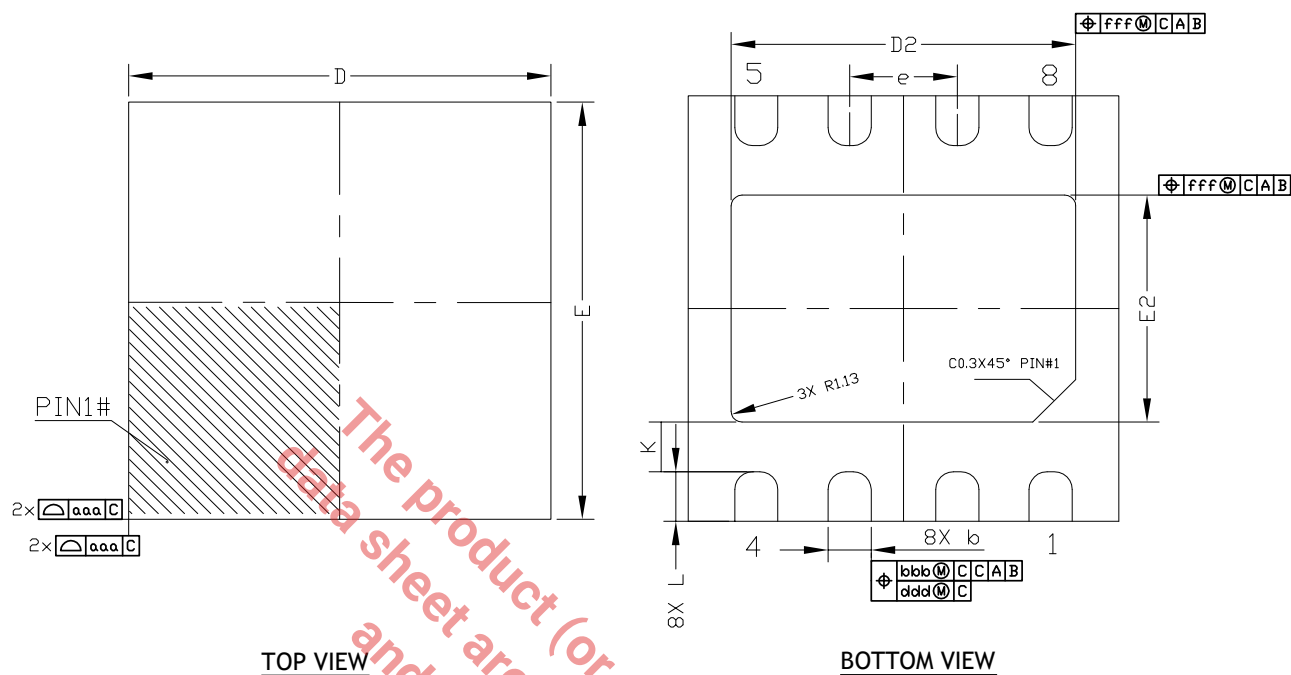


Figure 10. Recommended Layout

Mechanical Dimensions



DIM SYMBOL	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
A1	0	0.02	0.05
A3	-	0.20 REF	-
b	0.18	0.25	0.30
D	3.00BSC		
E	3.00BSC		
D2	2.20	2.40	2.60
E2	1.40	1.60	1.80
e	0.65BSC		
L	0.25	0.40	0.55
K	0.20		
aaa	0.15		
bbb	0.10		
ccc	0.10		
ddd	0.05		
eee	0.08		
fff	0.10		

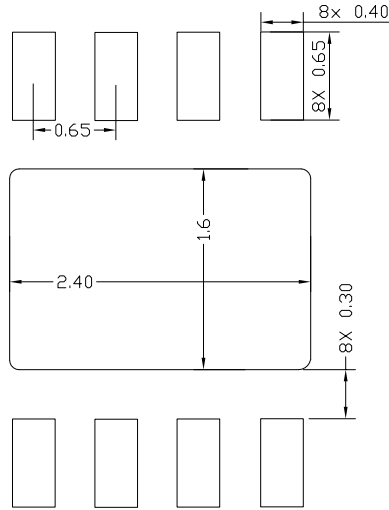
TERMINAL DETAILS

NOTE : ALL DIMENSIONS ARE IN MILLIMETERS, ANGLES ARE IN DEGREES.

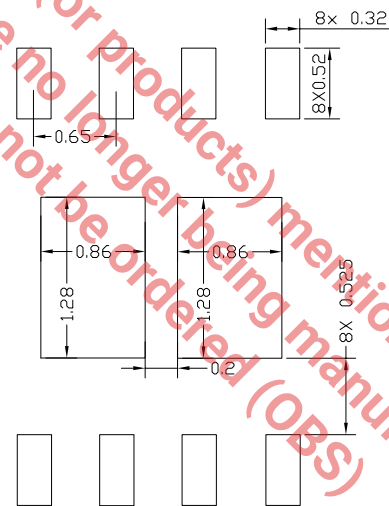
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Revision: D

Recommended Land Pattern and Stencil



TYPICAL RECOMMENDED LAND PATTERN



TYPICAL RECOMMENDED STENCIL

NOTE : ALL DIMENSIONS ARE IN MILLIMETERS, ANGLES ARE IN DEGREES.

Drawing No.: POD-00000088

Revision: D

Ordering Information⁽¹⁾

Part Number	Operating Temperature Range	Lead-Free	Package	Packaging Method
XR46203IHBTR	-40°C to 85°C	Yes ⁽²⁾	TDFN8 3x3	Tape and Reel

NOTE:

1. Refer to www.exar.com/XR46203 for most up-to-date Ordering Information.
2. Visit www.exar.com for additional information on Environmental Rating.

Revision History

Revision	Date	Description
1.0	June 2015	Initial Release.
1A	Oct 2016	New datasheet format, update Typical Application and update Package Description.
1B	Aug 2018	Update to MaxLinear logo. Update format.



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